

ICS 31.080

CCS L 55



**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 15879.4-2019

**Mechanical standardization of semiconductor devices -- Part 4:
Coding system and classification into forms of package
outlines for semiconductor device packages**

Issued on: August 30, 2019

Implemented on: December 1, 2019

**Issued by: State Administration for Market Regulation, China National
Standardization Administration**

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4.1 General

Foreword

GB/T 15879 "Mechanical Standardization of Semiconductor Devices" has been or is planned to be released as follows.

--- Part 1. General rules for drawing outlines of discrete device packages;

--- Part 2. Size;

--- Part 3. General rules for drawing outline drawings of integrated circuits;

--- Part 4. Classification and coding system for the outline of semiconductor device packages;

---Part 5. Recommended values for automated tape carrier integrated soldering (TAB);

--- Part 6. General rules for drawing outlines of surface mount semiconductor device packages.

This part is the fourth part of GB/T 15879.

This part is drafted in accordance with the rules given in GB/T 1.1-2009.

This section uses the translation method equivalent to IEC 60191-4.2013 "Mechanical standardization of semiconductor devices Part 4. Semiconductor devices

Classification and coding system for package shapes.

1 Scope

This part of GB/T 15879 specifies the classification and naming methods for the package shape of semiconductor devices, as well as packaging for semiconductor devices.

A systematic approach to general descriptive naming.

This descriptive naming method provides a useful communication tool, but does not ensure

that the same encoded package is interchangeable.

2 coding system for semiconductor device package outline

The coding scheme for the following semiconductor device package outlines is applicable to the relevant mechanical drawings and documents.

- a) Part I. A three-digit serial number (000~999) indicating the numbering sequence;
- b) Part II. a single letter representing the outline drawing (see Chapter 3);
- c) Part III. Represents a two-digit serial number derived from the outline drawing (00~99).

The prefix P represents a temporary figure number.

Example.

---101A00;

---050G13;

---P101F01.

3 Classification of semiconductor device package outlines

The classification rules for the outline of semiconductor device packages are as follows.

- a) Form A. single-ended lead;
- b) Form B. heat sink installation;
- c) Form C. bolt mounting;
- d) Form D. axial lead;
- e) Form E. surface mounting;
- f) Form F. single-ended heat sink installation;
- g) Form G. double column and four columns;
- h) Form H. No lead in the axial direction.

4.1 General

A standard coding system is a method of identifying the physical characteristics of a semiconductor device package. The coding system contains at least two representation packages

Shape type letters. The coding system can be extended by optional parts, and the user can select as needed to provide additional package information.